

M54640P

Stepper Motor Driver

REJ03F0042-0100Z

Rev.1.0

Sep.19.2003

Description

The M54640P is a semiconductor IC to drive a stepper motor by the bipolar method.

Features

- Bipolar and constant-current drive
- Wide current control range (20 – 800mA)
- Wide supply voltage drive range (10 – 40V)
- Built in flywheel diodes
- Current level can be changed by steps or continuously.
- Built in a thermal shutdown circuit

Application

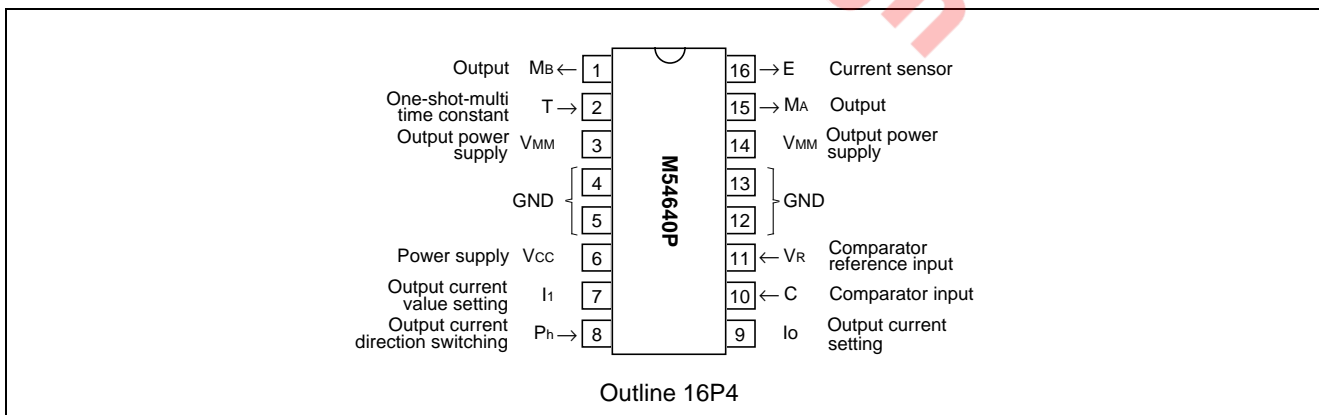
Printer, FDD, HDD, Fax

Function

The M54640P drives a stepper motor by the bipolar drive method to change the current direction of a single coil and controls the current direction with PHASE input pin. In order to obtain higher efficiency, the constant current drive system to control the coil current is introduced. The current value can be selected among four levels (0 to max.) by selecting the combination of three internal comparators by logic input. It also can be continuously changed by controlling the reference voltage. Conversion to voltage is conducted by the current value sensing resistor (R_s) and the voltage is sensed with each comparator, and then each comparator output triggers monomulti and the current is cut for a certain time (t_{OFF}) by utilizing the inductance of the coil.

Also, diodes needed for chopping and a thermal shutdown circuit as a countermeasure against overvoltage are built in this circuit.

Pin Configuration



Recommended Operating Condition

(Ta = 25°C, unless otherwise noted.)

Parameter	Symbol	Limits			Unit
		Min.	Typ.	Max.	
Supply voltage	V_{CC}	4.75	5	5.25	V
Output supply voltage	V_{MM}	10		40	V
Output current	I_O	20		800	mA
Logic input rise time	t_{PLH}			2	μ S
Logic input fall time	t_{PHL}			2	μ S
Thermal shutdown temperature	T_{ON}		175		°C

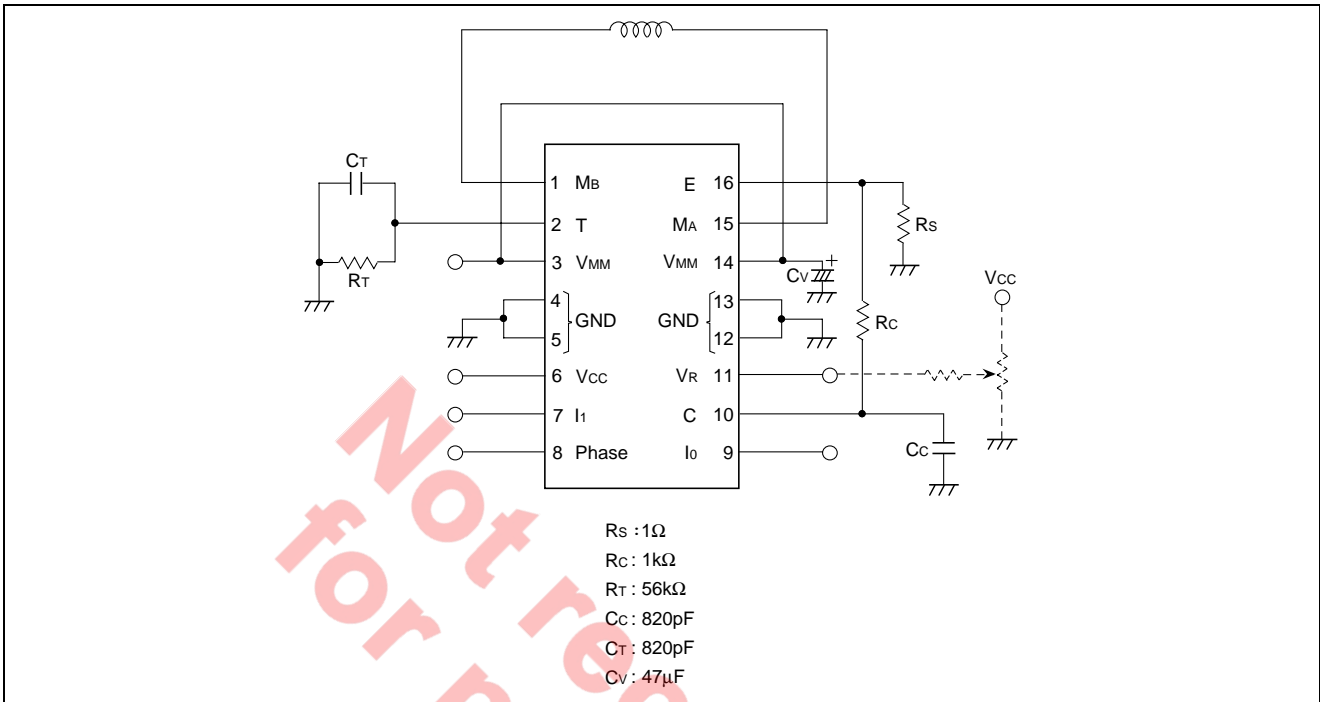
Electrical characteristics

(Ta = 25°C, V_{CC} = 5.0V, unless otherwise noted.)

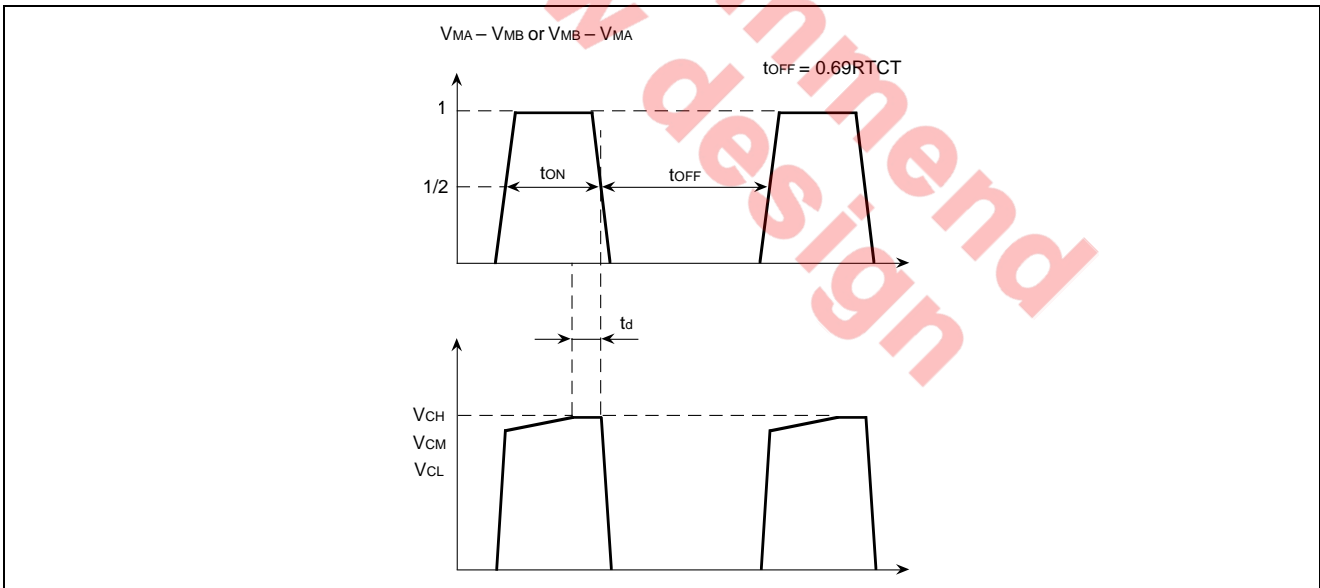
Parameter	Symbol	Limits			Unit	Test conditions	
		Min.	Typ.	Max.			
Logic input voltage	"H"	V_{IH}	2.0		V_{CC}	V	$V_{CC}=5V$
	"L"	V_{IL}	0		0.8		
Comparator threshold		V_{CH}	400	430	450	mV	$V_R=5V, I_0=I_1=0$
		V_{CM}	240	260	280		$V_R=5V, I_0=1, I_1=0$
		V_{CL}	75	90	100		$V_R=5V, I_0=0, I_1=1$
Comparator input current		I_{CO}	-20		20	μ A	
Output cutoff current		I_{OFF}			100	μ A	$I_0=I_1=1 (Ta=25^\circ C)$
Saturation voltage		V_{sat}			4.0	V	The voltage at the sensing resistor is not included. $I_O=500mA$
Cutoff time		t_{OFF}	25	30	35	μ S	$V_{MM}=10V, t_{ON} \geq 5\mu s$
Turnoff delay		t_d		1.6	2.0	μ S	$Ta=25^\circ C, dV/dt \geq 50mV/\mu s$
Supply current		I_{CC}			25	mA	$V_{CC}=5V$
Logic input current	"H"	I_{IH}			20	μ A	$V_I=2.4V$
	"L"	I_{IL}			-0.4	mA	$V_I=0.4V$

Switching Characteristics

Test Circuit



Switching Waveforms



Application Description

- PHASE INPUT
Phase input decides the output mode.

Phase	MA	MB
H	H	L
L	L	H

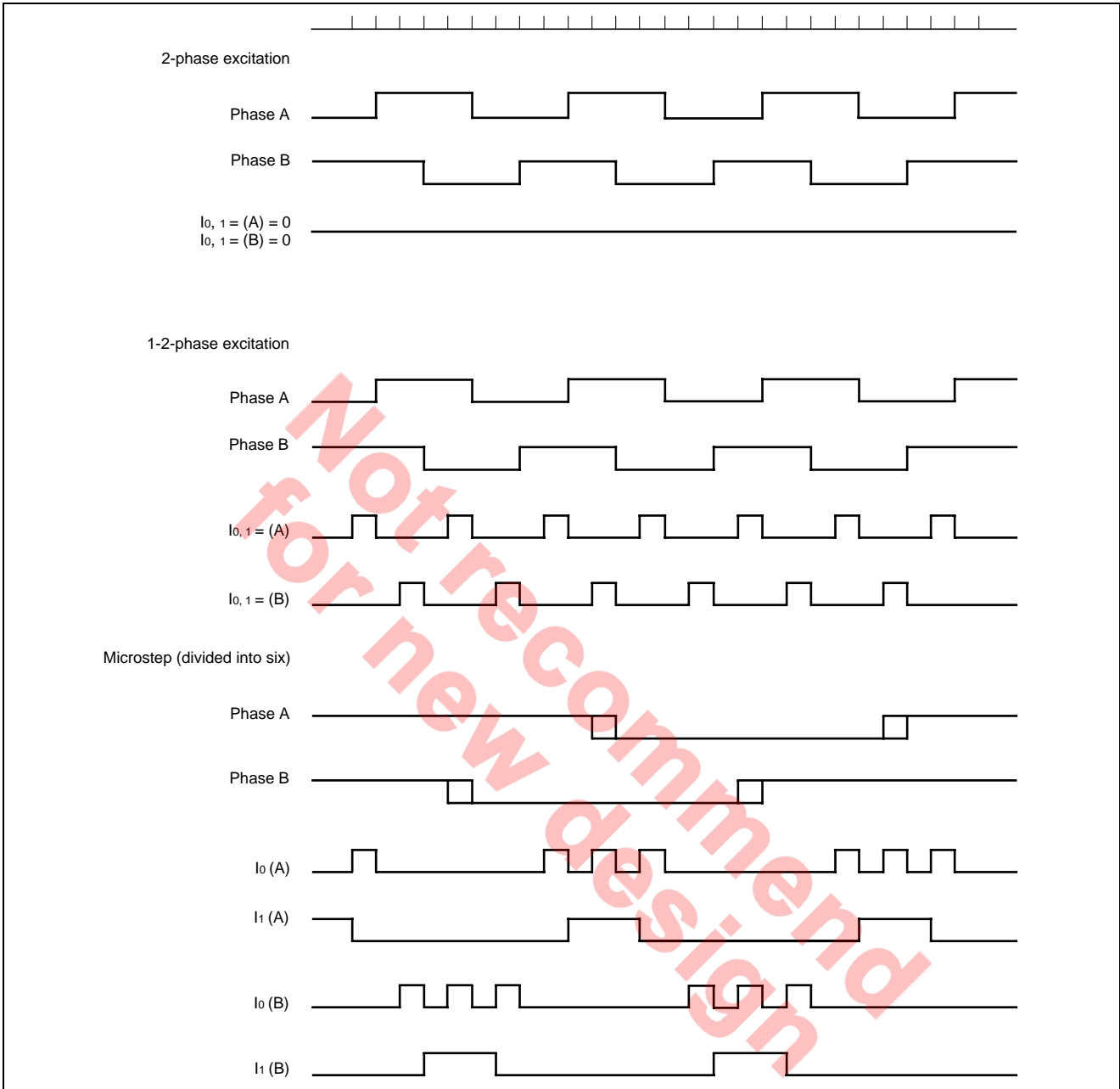
- I0, I1
I0 and I1 fixed based on the comparison voltage V_R decide the output current level.
The current level can be continuously changed by changing the voltage at V_R continuously.

I0	I1	Current level
H	H	0
L	H	Low
H	L	Average
L	L	High

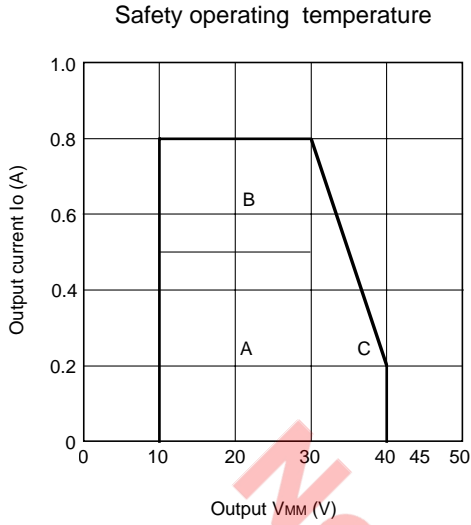
- Current sensor
When the voltage fall at the current sensing resistor and the selected current level becomes of the same level, the comparator triggers the monostable. Then, the output stage is cut off for a certain time (t_{OFF}). During this cutoff time, the current volume decreases slightly and falls short of the comparison level.
After the cutoff time (t_{OFF}), the output stage is in ON state again.
This operation is repeated.
- Single pulse generator
At the comparator output rise edge, the monostable is triggered.
The pulse width of the monostable at the external timing R_t and C_t is as follows.
$$t_{OFF} = 0.69 \times R_t C_t$$

Retrigger during t_{OFF} is neglected.
 - Analog control
The output current level can be continuously changed by changing the voltage at V_R or the feedback voltage to the comparator.

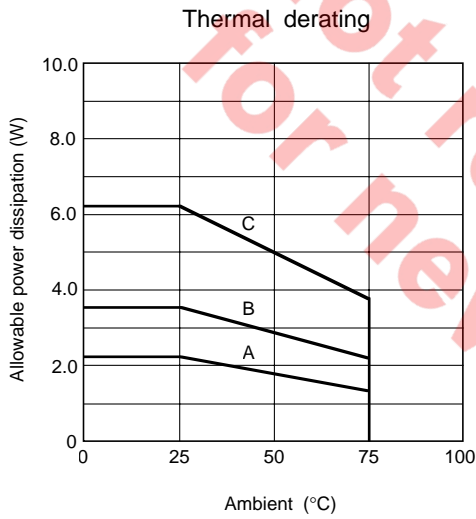
Timing Chart



Typical Characteristics (Absolute maximum ratings)

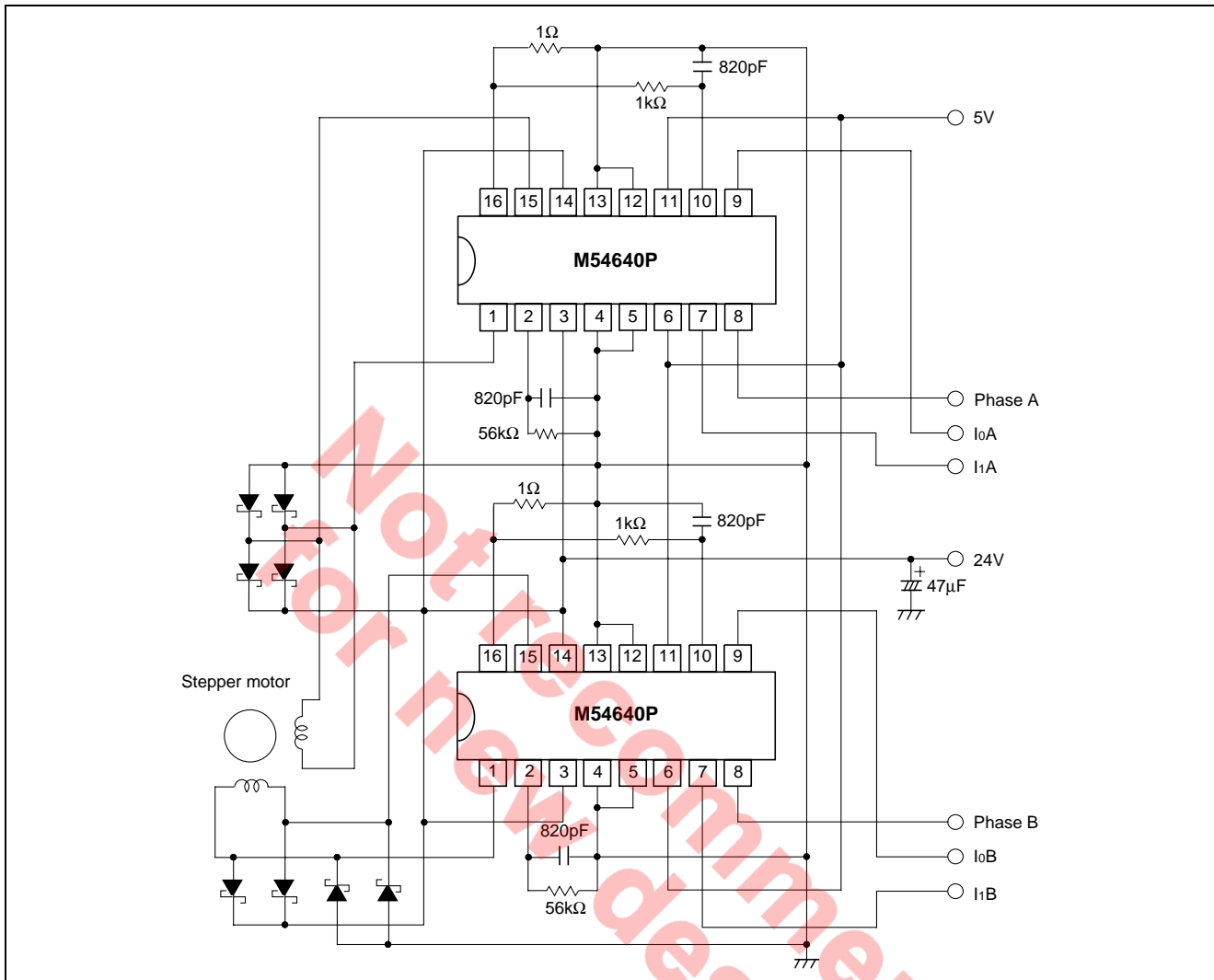


- A : Recommended
- B : Schottky diodes should be externally connected between output pins and power supply pins.
- C : Schottky diodes should be externally installed between output pins and power supply pins and between output pins and GND pin.



- $\theta_{j-c} = 10^{\circ}\text{C/W}$
- A : Mounted on a 25cm² glass epoxy board which is coated with copper on one side.
 $\theta_{c-a} = 45^{\circ}\text{C/W}$
- B : 10cm² aluminum heat sink (1t) is used.
 $\theta_{c-a} = 25^{\circ}\text{C/W}$
- C : 100cm² aluminum heat sink (1t) is used.
 $\theta_{c-a} = 10^{\circ}\text{C/W}$
 $T_{j(max)} = 150^{\circ}\text{C}$

Application Example



Precautions for use

(1) When the whole output current changes by a large margin (for example, when overheat protection operation causes intermittent flow of output current), the supply voltage may undergo a change. Therefore, selection and wiring of power supply should be conducted cautiously to avoid such a situation that the supply voltage exceeds the absolute maximum ratings.

(2) When the supply voltage changes by a large margin, the operation of this IC may become unstable. In this case, the change of supply voltage can be controlled by connecting a capacitor at the point near to IC pin between Vcc pin and GND pin. (See above application example.)

(3) Thermal shutdown function

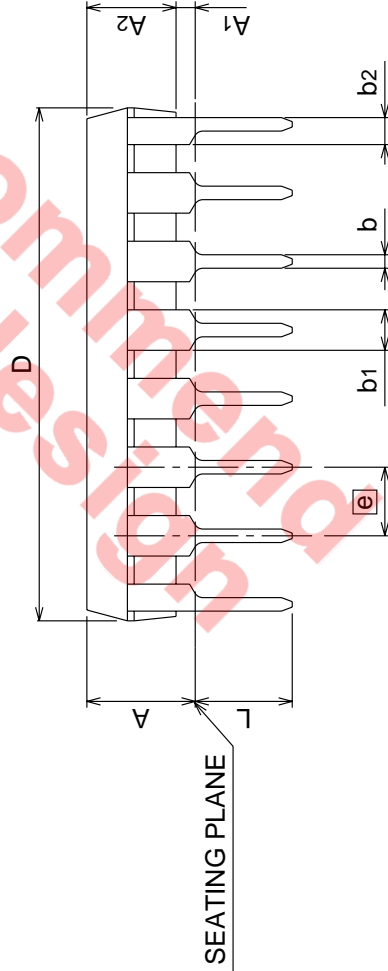
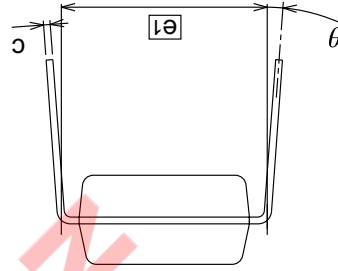
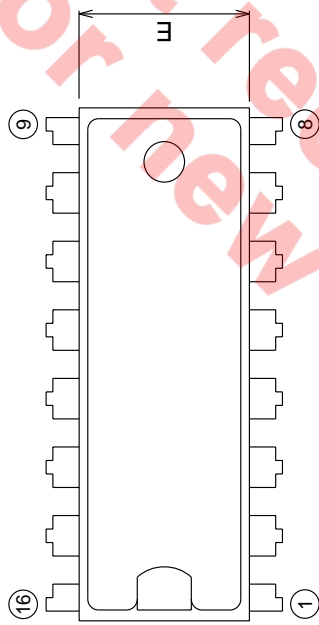
- The state of thermal shutdown operation may differ according to the way of wiring within a board. Therefore, sufficient board evaluation should be conducted before use. When the board is changed, operation on the replacing board should be evaluated.
- The circuit board on which this IC is mounted is designed to realize low impedance between power supply and output pin.

Therefore, it is desirable to take a safe measure such as fixing a fuse to avoid such a situation that the board is damaged by a fire when output pin is internally short-circuited by excessively applied surge voltage by accident.

Package Dimensions

16P4 **(MMP)** Plastic 16pin 300mil DIP

EIAJ Package Code DIP16-P-300-2.54	JEDEC Code —	Weight(g) 1.0	Lead Material Alloy 42/Cu Alloy
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Symbol	Dimension in Millimeters		
	Min	Nom	Max
A	—	—	4.5
A1	0.51	—	—
A2	—	3.3	—
b	0.4	0.5	0.59
b1	1.4	1.5	1.8
b2	0.9	1.0	1.3
c	0.22	0.27	0.34
D	18.8	19.0	19.2
E	6.15	6.3	6.45
e	—	2.54	—
ei	—	7.62	—
L	3.0	—	—
θ	0°	—	15°

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